

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1280acn#pbf

(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 1.202992**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004091	1000000	3400.68701172		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.345150	975000	286909.5625		
		Iron (Fe)	7439-89-6	0.008496	24000	7062.38964844		
		Phosphorus (P)	7723-14-0	0.000106	300	88.1136169434		
		Zinc (Zn)	7440-66-6	0.000248	700	206.152603149		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.354000</b>	<b>1000000</b>	<b>294266.21875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.027934	1000000	23220.6601562		
		<b>External Plating Total:</b>				<b>0.027934</b>	<b>1000000</b>	<b>23220.6601562</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.002832	1000000	2354.12963867		
<b>Internal Plating Total:</b>				<b>0.002832</b>	<b>1000000</b>	<b>2354.12963867</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001120	750000	931.011779785		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000373	250000	310.060150146		
<b>Die Attach Total:</b>				<b>0.001493</b>	<b>1000000</b>	<b>1241.07189941</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.194880	240000	161996.03125		
		Bromine (Br)	40039-93-8	0.008120	10000	6749.8359375		
		Silica (SiO2)	60676-86-0	0.584640	720000	485988.15625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.024360	30000	20249.5039062		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		<b>Encapsulation Total:</b>				<b>0.812000</b>	<b>1000000</b>	<b>674983.5</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000642	1000000	533.669250488		
					<b>TOTAL MASS (g) :</b>	<b>1.202992</b>		